# «HIMIK-PLUS»



#### **Technical Datasheet**

## Adhesive 88 Viscous. Possibility of gluing correction

# Adhesive 88 Viscous possibility of gluing correction - contact adhesive for bonding plastics, wood, leather, metal, rubber and other porous materials.

#### AREAS OF APPLICATION.

Glue for bonding most known materials in any combination (plastics, wood, leather, metal, rubber, textiles, ceramics) and gluing various products to surfaces made of wood, metal, brick, concrete and many others. It is especially effective when working with porous materials. It differs in smooth fixation of glued products, which allows you to adjust the position of the glued parts in the first minutes after fixing. Suitable for indoor and outdoor use. Application by brush, spatula.

#### PROPERTIES.

- High strength and good thermal stability of the assemblies.
- Resistance to hydrolysis (water resistance), acids and mineral oil.
- Good connection flexibility, including at low temperatures.
- Easy to apply.
- Excellent adhesion to most substrates.
- The average open time allows you to work with large surfaces.

#### TECHNICAL DATA.

proprene rubber and synthetic
resins in organic solvents.
Light yellow
20 – 23
арргох. 2500
approx. 0.83
<i>35</i>
<i>50 – 60</i>
<i>60 – 90</i>
70
100

#### PACKAGING.

Metal can 620 g (800 ml) 12 units in cardboard box Conical metal container 2.3 rg (3 L) 4 units in cardboard box

## STORAGE.

Storage time 12 months. Recommended storage temperature: 5 - 25 °C. Storage in original containers away from sources of fire.

### SAFETY.

Highly flammable and irritant. When using do not smoke, work away from sources of fire and sparks. The glue is made using low-toxic solvents, nevertheless work with glue in well-ventilated rooms, and in industrial conditions in rooms with forced-air and exhaust ventilation. Details of safe use in the safety data sheet.

This product data sheet is only valid in conjunction with the latest edition of the corresponding Safety Data Sheet. Any updating of safety-relevant information—in accordance with statutory requirements — will only be reflected in the Safety Data Sheet, copies of which will be revised and distributed. Information relating to the current classification and labeling, applications and processing method sand further data Read material safety data sheet before use.

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#### **INSTRUCTIONS FOR USE.**

## Substrates preparation:

The substrates to be assembled must be dry, dust free and not have any traces of grease or other contaminants that could adversely affect the adhesive performance. They may be cleaned with RKV -1 solvent, MEK or ethyl acetate. Check the compatibility of the solvent used with the substrates. If necessary, rub down metal surfaces beforehand and clean them. When using solvents, extinguish all sources of ignition and carefully follow the safety and handling instructions given by the manufacturer.

Temperature of adhesive and substrates have to be between 15 - 25 °C.

#### Application:

Apply a regular layer with a brush or spatula to each substrate.

Let solvents evaporate (5 to 15 minutes, depending on temperature, hygrometry and substrates). Take care not to exceed open time, otherwise, bonding will be defective.

Assemble precisely both parts and press briefly but firmly and evenly on the whole surface. Once the two substrates are assembled, they can't be repositioned or separated. With rigid materials, assembling has to be followed by an even and maximum pressure applied across the entire surface without irreversible deformation of substrates.

In damp and cold weather, ensure that materials and adhesive are at a correct temperature in order to prevent formation of dew as the solvents evaporate, which could result in defective bonding.

#### The use of thermal activation of the adhesive film.

If the "open time" of the adhesive film has expired (the film has become inactive) or according to the requirements of the technology, the properties of the adhesive film can be restored by thermal activation by heating in a heating cabinet or in a thermal shock under an infrared lamp. The temperature of thermal activation is 45-60 ° C.

#### Cleaning:

Tools can be cleaned with MEK or ethyl acetate immediately after use (before curing). After curing cleaning mechanically.

#### CONSUMPTION.

125 to 150 g/m² to each surface depending on substrates. For very porous materials, a higher amount may be necessary.

#### PRECAUTIONS FOR USE.

Adhesive **88 Possibility of gluing correction** cannot be used for bonding expanded polystyrene or untreated polyethylene, polypropylene, fluorinated polymers or plasticised PVC.

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